PRODUCT SPECIFICATION

Lastek 30 PA



Silver brazing paste

CLASSIFICATION

AWS A5.8: 2011-AMD1 BAg-1

GENERAL DESCRIPTION

Low bonding temperature.

Used for furnace soldering in controlled atmosphere and for oxy-acetylene soldering.

High silver content.

Easy and economic to use.

Penetrates deeply in tight joints.

APPLICATIONS

Jewellery, wire cloth, chemical apparatus, electrical contacts, medical instruments, bicycle frames, hydraulic components, music instruments, hardmetal, ...

Bonding temperature: 620°C (1150°F)

Electrical resistivity: 0.074 ohm.mm²/m (2.91 .10-6 ohms/in/in²)

CHEMICAL COMPOSITION (%) (Typical values, all weld metal)

Ag: 44.00 - 46.00	Cu : 14.00 - 16.00	Cd : 23.00 - 25.00	Zn : 14.00 - 18.00	

MECHANICAL PROPERTIES (Typical values, all weld metal)

Yield Strength	Tensile Strength	Elongation	Impact Strength
N/mm²	N/mm²	5d (%)	Charpy V notch (ISO-V)
	450 MPa		

GENERAL INFORMATION

Welding positions	NA
Shielding gas	NA
Packing	30 ml in a syringe
Polarity	NA

Tips & tricks

Clean the joint area and apply the paste in the desired quantity in the joint gap.

Heat the joint area and the paste gradually to remove the binder (do not point the flame directly in the paste;

take care that the paste is heated by conduction).

Flux and alloy will flow in the direction of the hottest part.

Stop heating and allow the alloy to solidify before removing any fixtures.

Remove flux residues in warm water.

When soldering large surfaces, apply the solder in lines or points, do not cover the whole surface with solder.

Take care that the solder flows from the inside of the joint to the outside.

The information in this document is based on intensive tests and is accurate to the best of our knowledge. Do note that these values are only typical values for tests in accordance to prescribed standards. The suitability of the product should always be confirmed by qualification tests before use in any application. The information can be changed without previous notice.

www.lastek.be PSEN_L30PA_N0525_TW